



Material Composition Declaration

EPC2207

Company Name	Efficient Power Conversion (EPC)	Issue Date:	8/19/2020
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	3.8 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)		
Chip	Silicon	7440-21-3	3.0643	79.6294	82.7366	796294
	Silicon oxide	7631-86-9	0.0107	0.2781		2781
	Silicon nitride	12033-89-5	0.0075	0.1955		1955
	Gallium nitride	25617-97-4	0.0208	0.5399		5399
	Aluminum	7429-90-5	0.0397	1.0319		10319
	Aluminum nitride	24304-00-5	0.0065	0.1700		1700
	Titanium	7440-32-6	0.0004	0.0115		115
	Titanium nitride	25583-20-4	0.0037	0.0966		966
	Copper	7440-50-8	0.0013	0.0345		345
	Tungsten	7440-33-7	0.0009	0.0247		247
	Polyimide		0.0279	0.7246	7246	
Under Bump Metal	Titanium	7440-32-6	0.0003	0.0087	0.0347	87
	Nickel	7440-02-0	0.0000	0.0000		0
	Copper	7440-50-8	0.0010	0.0260		260
Solder Bump	Copper	7440-50-8	0.0332	0.8626	17.2287	8626
	Nickel	7440-02-0	0.0198	0.5146		5146
	Tin	7440-31-5	0.5990	15.5662		155662
	Silver	7440-22-4	0.0110	0.2853		2853
Sum in total:			3.8482	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.